

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5766270

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
NATIONAL INSTITUTE FOR MATERIALS SCIENCE	10/09/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	ROHM CO., LTD.
<b>Street Address:</b>	21, SAIIN MIZOSAKI-CHO UKYO-KU
<b>City:</b>	KYOTO-SHI KYOTO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	615-8585
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Patent Number:	7972577
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(202)293-0445
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	202-293-0444
<b>Email:</b>	mailpto@giplaw.com
<b>Correspondent Name:</b>	GLOBAL IP COUNSELORS, LLP
<b>Address Line 1:</b>	1233 TWENTIETH STREET, N.W.
<b>Address Line 2:</b>	SUITE 600
<b>Address Line 4:</b>	WASHINGTON, D.C. 20036
<b>ATTORNEY DOCKET NUMBER:</b>	RHM-US030695-A
<b>NAME OF SUBMITTER:</b>	JOHN C. ROBBINS
<b>SIGNATURE:</b>	/John C. Robbins/
<b>DATE SIGNED:</b>	10/11/2019
<b>Total Attachments: 1</b>	
source=RHM-US030695-A(US7972577) Assignment_NIMS#page1.tif	

## ASSIGNMENT

WHEREAS, NATIONAL INSTITUTE FOR MATERIALS SCIENCE, a Japanese Corporation, located and doing business at  
2-1, SENGUN I-CHOME, TSUKUBA-SHI  
IBARAKI, JAPAN 305-0047,  
(hereinafter ASSIGNOR),

is the owner of the entire right, title and interest, by assignment recorded in the United States Patent and Trademark Office on  
February 18, 2010 at Reel No. 023958 Frame 0075, in the invention entitled CHIP USING METHOD AND TEST CHIP, which is  
the subject of Letters Patent of the United States Patent No. 7,972,577, issued on July 5, 2011,

WHEREAS, ROHM CO., LTD., a Japanese Corporation, located and doing business at  
21, SAIN MIZOSAKI-CHO UKYO-KU  
KYOTO-SHI KYOTO, JAPAN 615-8585,

is desirous of acquiring the right, title and interest in and to the aforementioned invention and the aforementioned United States  
Patent and any and all subsequent Letters Patent to be obtained on said invention;

## NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN that for and in consideration of good and valuable consideration paid to ASSIGNOR by said ASSIGNEES,  
the receipt and sufficiency of which is hereby acknowledged, said ASSIGNOR, by these presents does hereby sell, assign, set over and  
transfer unto the said ASSIGNEES its successors, legal representatives or assigns, the entire right, title and interest in and to the  
aforesaid inventions in and for the United States and all countries foreign thereto; and in, to and under the aforesaid United States  
Patents and any corresponding foreign applications and any divisional, continuing, substitute or reissue applications or supplementary  
disclosures which may be or have been filed on said inventions in any country; and the right to file said foreign applications and claim  
priority under the provisions of the International Convention; and any subsequent Letters Patents of the United States or any foreign  
country issued or granted on said inventions;

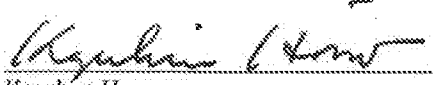
AND ASSIGNOR HEREBY authorizes and requests the U.S. Patent and Trademark Office or other issuing authority to issue  
any and all patents on said inventions and/or said applications to said ASSIGNEES, as sole assignees; and ASSIGNOR further hereby  
authorizes said ASSIGNEES to file and prosecute any of said foreign applications in their own names;

AND ASSIGNOR HEREBY covenants that it has the full right to convey the entire right, title and interest herein assigned and  
that it has not executed and will not execute any assignment or other instrument in conflict herewith;

AND ASSIGNOR HEREBY conveys any and all claims for damages, royalties, profits, interest, costs, and fees by way of  
past, present and future infringements of any of the rights included above, as well as but not limited to the right to collect such damages,  
royalties, profits, interest, costs, and fees for infringements occurring from the date of publication of the application of the aforementioned  
United States Patent to the date of issuance of the aforementioned United States Patent, with the right, but not the obligation, to sue for  
and collect such damages, royalties, profits, interest, costs, and fees for said infringements of the aforementioned United States Patent;

AND ASSIGNOR HEREBY further covenants and agrees to communicate to said ASSIGNEES, or its legal representatives,  
successors or assigns, any facts relating to said inventions, including evidence for interference purposes or other proceedings, whenever  
requested, and to testify in any interference or in any other legal proceeding, when requested, and to execute and deliver on request all  
lawful papers required to make any of the foregoing provisions effective; and to perform the aforesaid communicating, executing and  
delivering, without any payment except expenses and to perform the aforesaid testifying for reasonable compensation; and generally to  
do every thing possible to aid the said ASSIGNEES, its successors, legal representatives or assigns to obtain and enforce proper patent  
protection on and for said inventions in all countries, and likewise I make these provisions binding upon my heirs, legal representatives  
and/or administrators.

The undersigned hereby grants the firm of **Global IP Counselors, LLP** the power to insert in this Assignment any further  
identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for  
recording of this Assignment.

  
Name: Kazuhiro Hono  
Title: Director, External Collaboration Division  
On behalf of Assignor

Date: October 9, 2019

NATIONAL INSTITUTE FOR MATERIALS SCIENCE

S:\09-SEP19-YA\RHM-US030695 & 030695A-Assignments\RHM-US030695-A-Assignment.doc